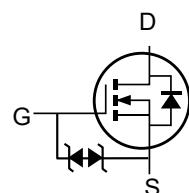
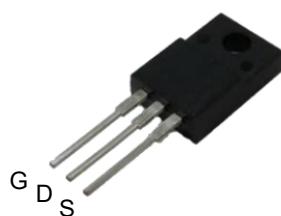


N-Channel Super Junction MOSFET

MCR65Z130CTF



Features

- Very Low FOM ($R_{DS(on)} \times Q_g$)
- Extremely low switching loss
- Excellent stability and uniformity
- 100% Avalanche Tested
- Built-in ESD Diode
- Fast Recovery Time

Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- AC to DC Converters
- Telecom, Solar

Table 1. Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	MCR65Z130CTF	Unit
Drain-Source Voltage	V_{DSS}	650	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current at $T_c = 25^\circ\text{C}$	I_D	25 *	A
Continuous Drain Current at $T_c = 100^\circ\text{C}$	I_D	15.8*	A
Pulsed drain current (Note 1)	I_{DM}	75*	A
Power Dissipation($T_c=25^\circ\text{C}$)	P_D	34	W
Single pulse avalanche energy (Note2)	E_{AS}	454	mJ
Avalanche current	I_{AR}	3.1	A
Gate source ESD(HBM-C=100pF, R=1.5KΩ)	$V_{ESD(G-S)}$	2000	V
MOSFET dv/dt ruggedness, $V_{DS} = 0\dots 400\text{V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 400\text{V}$, $IDS \leq ID$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	°C
* limited by maximum junction temperature			

Table 2. Thermal Characteristic

Parameter	Symbol	MCR65Z130CTF		Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	3.65		°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	80		°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =1mA	650	--	--	V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V, V _{GS} =0V	--	--	2	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I _{DSS}	V _{DS} =650V, V _{GS} =0V	--	350	--	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	--	--	±1	μA
Gate Threshold Voltage	V _{GS} (th)	V _{DS} =V _{GS} , I _D =1.1mA	2.5	--	5.0	V
Drain-Source On-State Resistance	R _{DSS(on)}	V _{GS} =10V, I _D =10.2A	--	115	130	mΩ
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =400V, V _{GS} =0V, F=1.0MHz	--	2840	--	pF
Output Capacitance	C _{oss}		--	61	--	pF
Reverse Transfer Capacitance	C _{rss}		--	3.8	--	pF
Total Gate Charge	Q _g	V _{DS} =520V, I _D =14.3A, V _{GS} =10V	--	65	--	nC
Gate-Source Charge	Q _{gs}		--	12	--	nC
Gate-Drain Charge	Q _{gd}		--	19	--	nC
Switching times						
Turn-on Delay Time	t _{d(on)}	V _{DD} =325V, I _D =14.3A, R _G =25Ω	--	56	--	nS
Turn-on Rise Time	t _r		--	31	--	nS
Turn-Off Delay Time	t _{d(off)}		--	250	--	nS
Turn-Off Fall Time	t _f		--	20	--	nS
Source- Drain Diode Characteristics						
Forward on voltage	V _{SD}	T _j =25°C, I _S =14.3A, V _{GS} =0V	--	--	1.3	V
Reverse Recovery Time	t _{rr}	V _R =400V, I _F =14.3A, dI _F /dt=100A/μs	--	150	--	nS
Reverse Recovery Charge	Q _{rr}		--	1.0	--	μC

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.I_{AS}=3.1A V_{DD}=100V,R_G=25Ω,Starting T_J=25°C

Typical Characteristics

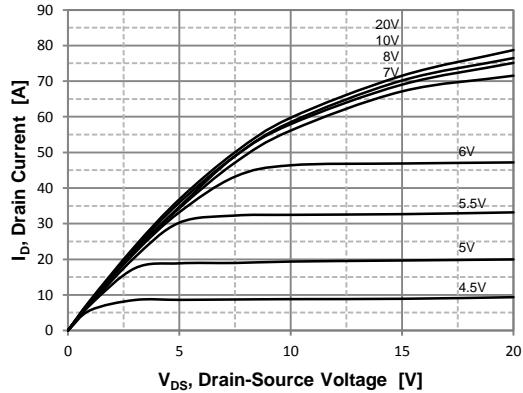


Figure 1. On Region Characteristics

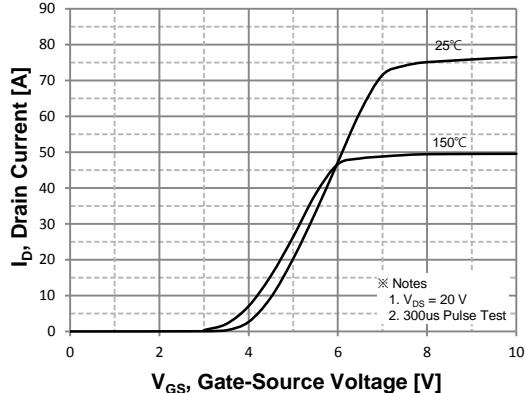
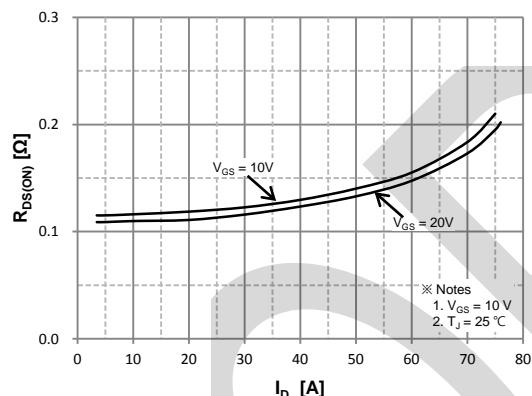
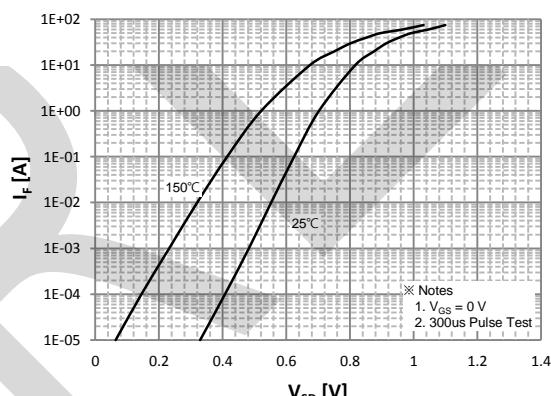


Figure 2. Transfer Characteristics



**Figure 3. On Resistance Variation vs.
Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage
Variation with Source Current
and Temperature**

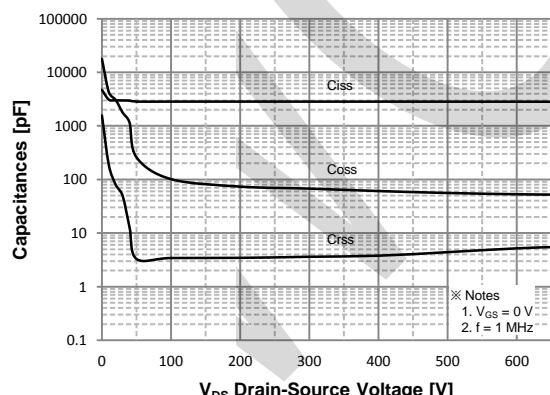


Figure 5. Capacitance Characteristics

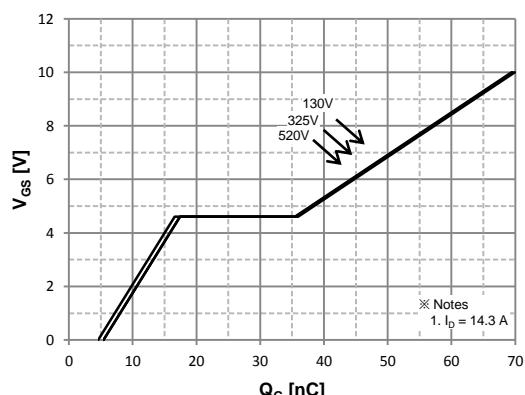


Figure 6. Gate Charge Characteristics

Typical Characteristics

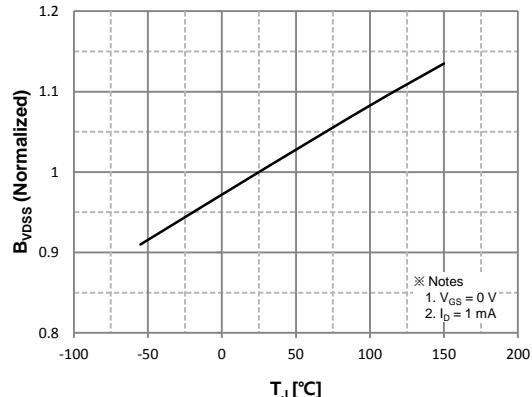


Figure 7. Breakdown Voltage Variation vs. Temperature

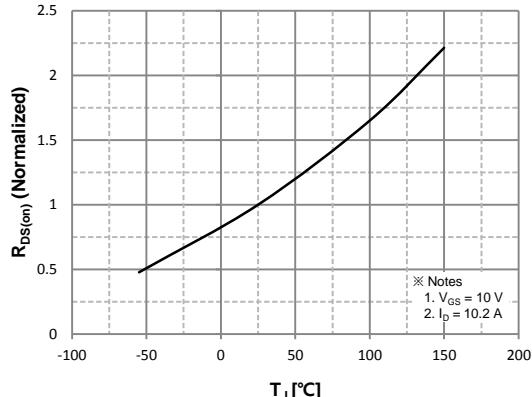


Figure 8. On-Resistance Variation vs. Temperature

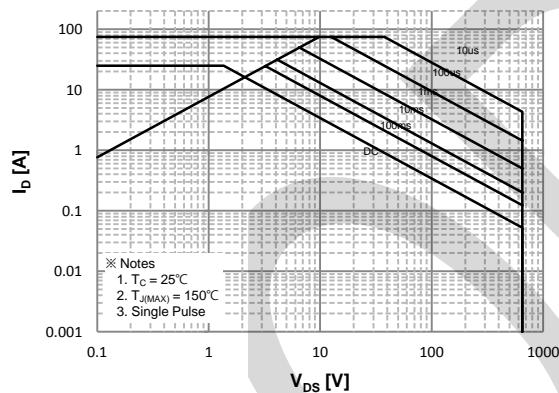


Figure 9. Maximum Safe Operating Area

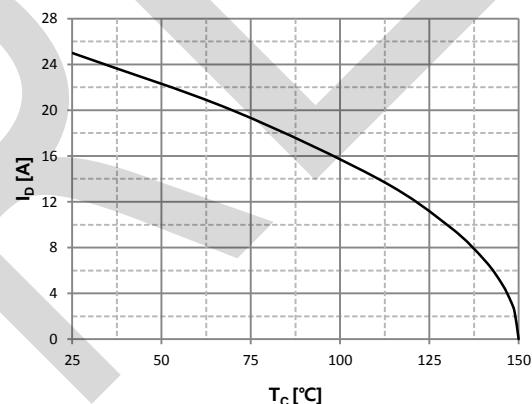


Figure 10. Maximum Drain Current vs. Case Temperature

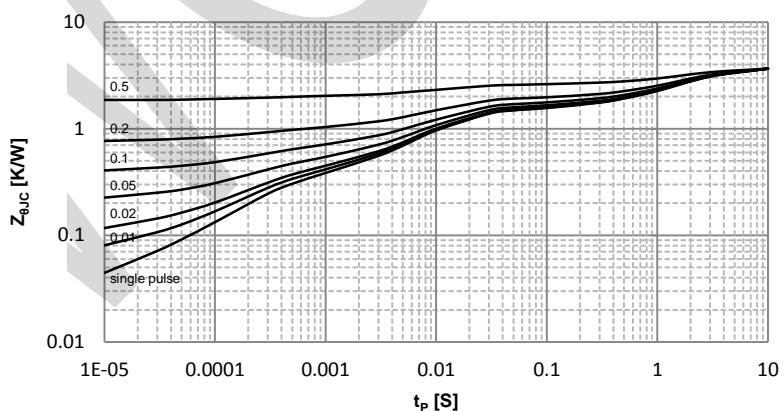
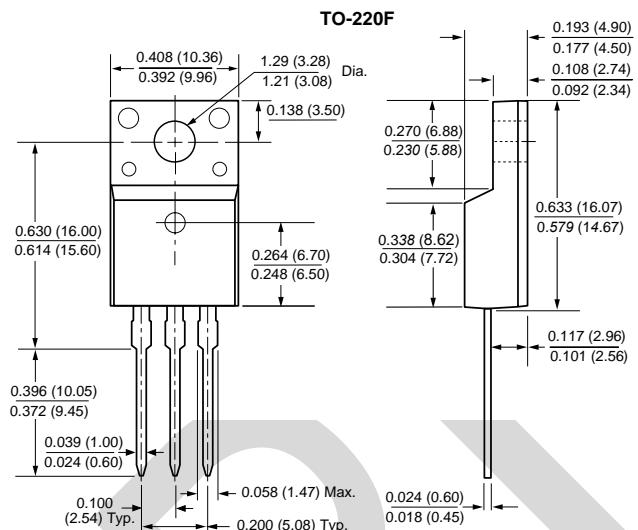


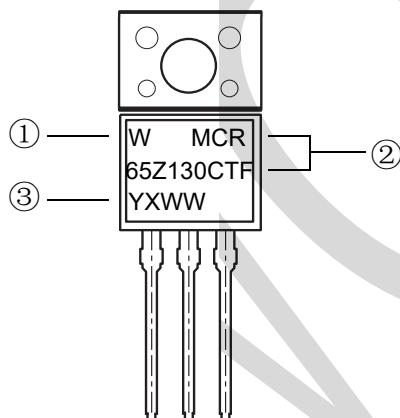
Figure 11. Transient Thermal Response Curve

PACKAGE OUTLINE DIMENSIONS

TO-220F Package Information



Marking Information



Y X WW

WW:Week code(01 to 53)
X:Internal identification code
Y:Year code(ex:0=2020)